



PRODUCT INFORMATION LETTER

PIL IPD-DIS/13/8034
Dated 29 Jul 2013

**SO8 Super High Density leadframe qualification in ST
in-house plant (China)**

Sales Type/product family label	ACS102-6T1-TR
Type of change	Package assembly process change
Reason for change	To increase its industrial capacity
Description	Implementation of Super High Density frame on products housed in SO8 package. -The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet -The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged. -The footprint recommended by ST remains the same. -There is no change neither in the packing modes nor the standard delivery quantities.
Forecasted date of implementation	22-Aug-2013
Forecasted date of samples for customer	22-Jul-2013
Forecasted date for STMicroelectronics change Qualification Plan results availability	22-Jul-2013
Involved ST facilities	ST in-house plant (China)

DOCUMENT APPROVAL

Name	Function
Paris, Eric	Marketing Manager
Duclos, Franck	Product Manager
Cazaubon, Guy	Q.A. Manager

PIL

Product/Process Information Letter

SO8 Super High Density leadframe qualification in ST in-house plant (China)

Notification number:	IPD-DIS/13/8034	Issue Date	22/07/2013
Issued by	Aline AUGIS		
Product series affected by the change		ACS102-6T1-TR	

Reason for change

ST upgrades its products housed in SO8 package with a new Super High Density frame in order to increase its industrial capacity.

Effects of change

Implementation of Super High Density frame on products housed in SO8 package.

- The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet
- The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged.
- The footprint recommended by ST remains the same.
- There is no change neither in the packing modes nor the standard delivery quantities .

Product identification and traceability

Traceability and identification is ensured by:

- Specific **internal product codification** for devices with Super High Density leadframe. This code is mentioned on the inner and outer packing box.
- **QA lot number** .

Qualification complete date	8 th of April, 2013
------------------------------------	--------------------------------

Forecasted sample availability

Product family	Package	Commercial part Number	Availability date
Thyristors (SCR) and AC Switches	SO8	ACS102-6T1-TR	Now

Change implementation schedule

Sales types	Estimated production start	Estimated first shipments
ACS102-6T1-TR	Week 28-2013	Week 34-2013



Public Products List

PIL Title : SO8 Super High Density leadframe qualification in ST in-house plant (China)

PIL Reference : IPD-DIS/13/8034

PIL Created on : 31-JUL-2013

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change:

ST COMMERCIAL PRODUCT

ACS102-6T1-TR

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY TWO AUTHORIZED ST REPRESENTATIVES, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners

© 2013 STMicroelectronics - All rights reserved.

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -
Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com